

**In the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Canceled).
  
2. (Original) A process for manufacturing integrated circuits, comprising the steps of:
  - a.) providing a substrate
  - b.) forming a plurality of transistors on said substrate;
  - c.) forming conductive interconnects on said substrate to interconnect said transistors in a predetermined electrical configuration;
  - d.) forming, among said interconnects, pairs of conductive contact pads; and
  - e.) automatically forming polymeric conductors to electrically connect respective pairs of conductive contact pads in a self-aligned step.
  
3. (Original) The process of claim 2, wherein said pairs include a first metal and second metal, and said polymeric conductors attach asymmetrically with a first terminus attached to said first metal and second terminus attached to said second metal.
  
4. (Original) The process of Claim 2, wherein said polymeric conductors each consist of an oligomer of a precisely predetermined number of units.
  
5. (Original) The process of Claim 2, wherein said polymeric conductors each consist of an oligomer of a precisely predetermined number of units, and wherein a first step forms a first set of oligomers having a first predetermined length, and a second step forms a second set of oligomers having a second predetermined length.